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SURFACE MOUNT LED TAPE AND REEL



Lead-Free Parts

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LHIR9553

DATA SHEET

DOC. NO : QW0905-LHIR9553

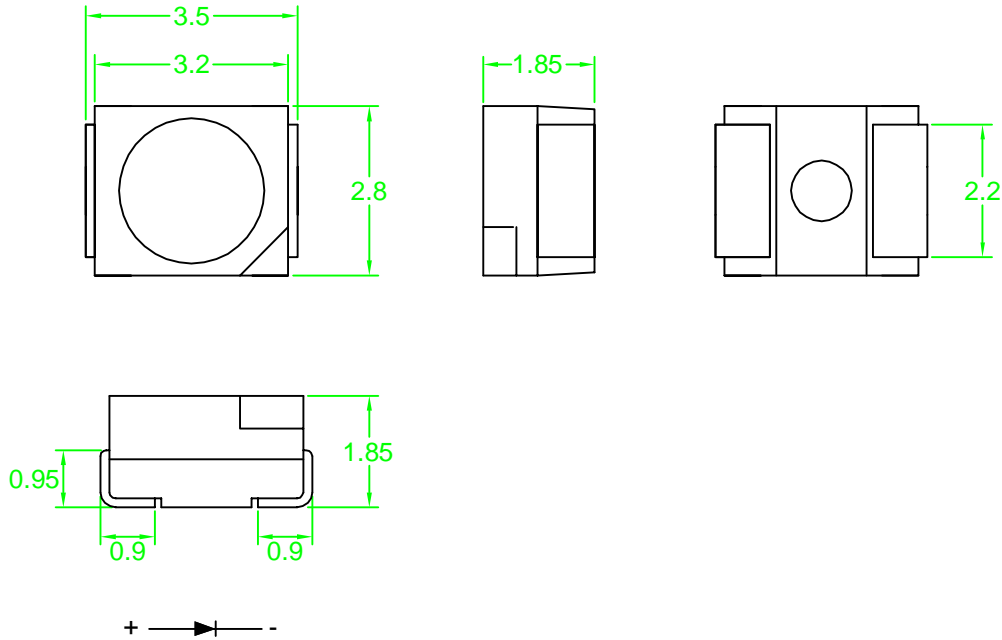
REV : A

DATE : 16 - Mar. - 2009



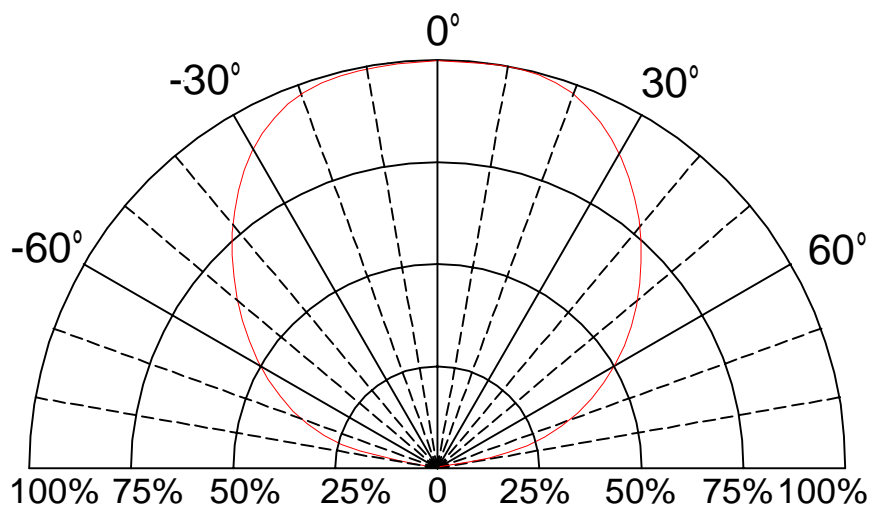


Package Dimensions



Note : 1.All dimension are in millimeter tolerance is $\pm 0.2\text{mm}$ unless otherwise noted.
2.Specifications are subject to change without notice.

Directivity Radiation





Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Ratings	UNIT
		HIR	
Forward Current	IF	50	mA
Peak Forward Current (300PPS,10 μ s Pulse)	IFP	1	A
Power Dissipation	PD	100	mW
Reverse Voltage	Vr	5	V
Operating Temperature	Topr	-55 ~ +100	
Storage Temperature	Tstg	-55 ~ +100	

Electrical Optical Characteristics (Aa=25)

PARAMETER	SYMBOL	Min.	Typ.	Max.	UNIT	TEST CONDITION
Radiant Intensity	Le	1.1	1.9		mW/sr	IF=20mA
Aperture Radiant Incidence	Ee	0.15	0.27		mW/cm ²	IF=20mA
Peak Emission Wavelength	peak		850		nm	IF=20mA
Spectral Line Half Width			50		nm	IF=20mA
Forward Voltage	VF	1.2		1.6	V	IF=20mA
Reverse Current	IR			100	μ A	VR=5V
Viewing Angle	2 1/2		120		deg	

Note : 1.The forward voltage data did not including $\pm 0.1V$ testing tolerance.
2. The radiant intensity data did not including $\pm 15\%$ testing tolerance.



2.Handling Precaution

① Do not poke the silicone encapsulant with sharp object

② Hold the LED only by the body

③ Do not attach assembled PCB

④ Do not touch the silicone encapsulant

⑤ Clean the silicone surface with white cotton bud with minimal pressure

⑥ Use pick and place nozzle per recommendation in datasheet



Typical Electro-Optical Characteristics Curve

HIR CHIP

Fig.1 Forward Current vs. Forward Voltage

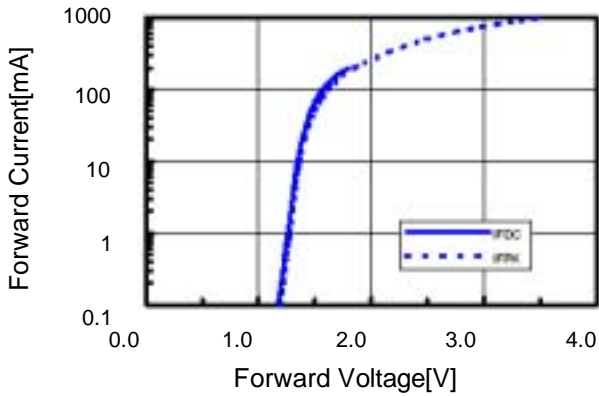


Fig.2 Relative Radiant Power vs. Wavelength

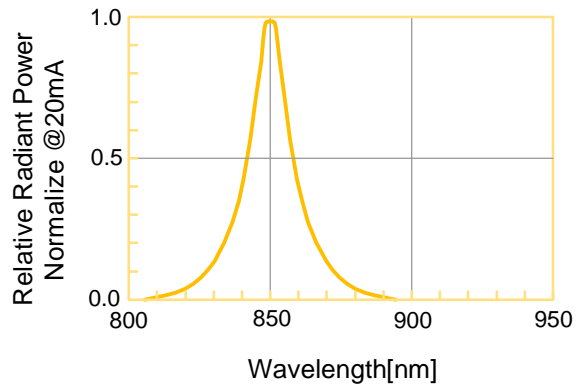


Fig.3 Relative Radiant Power vs. Forward DC Current

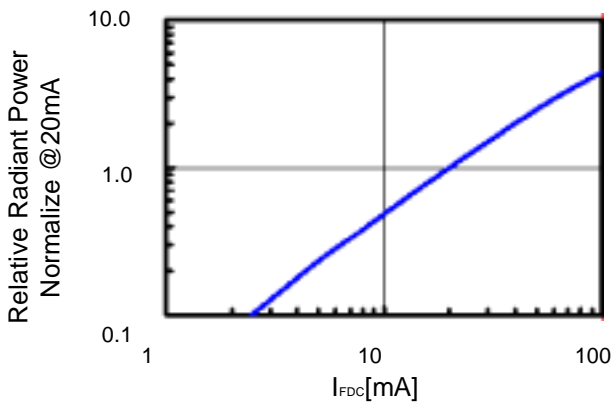


Fig.4 Relative Radiant Power vs. Forward Peak Current

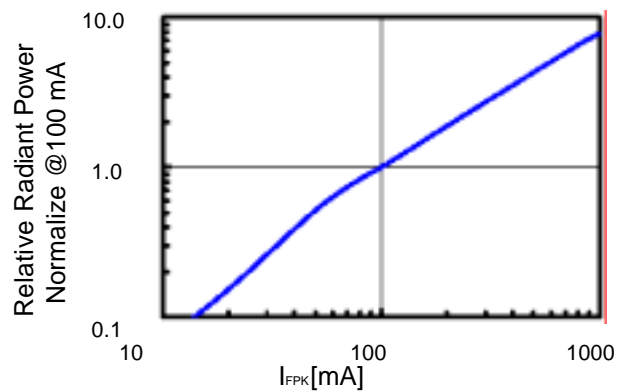


Fig.5 Forward DC Voltage vs. Temperature

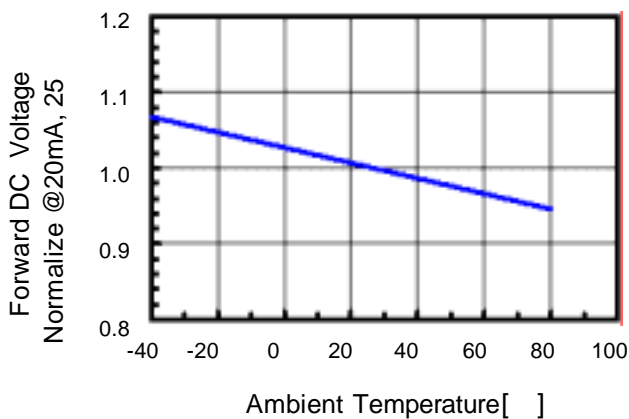
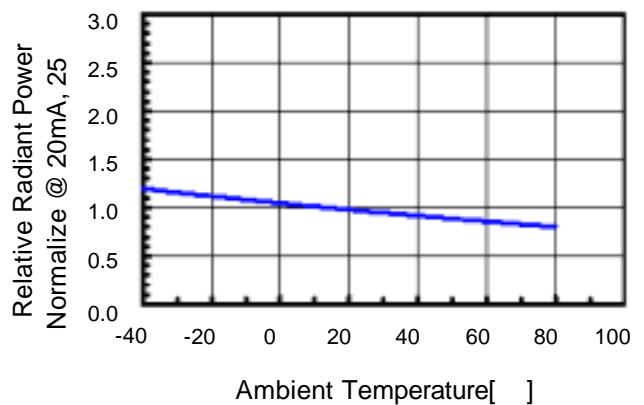


Fig.6 Relative Radiant Power vs. Temperature



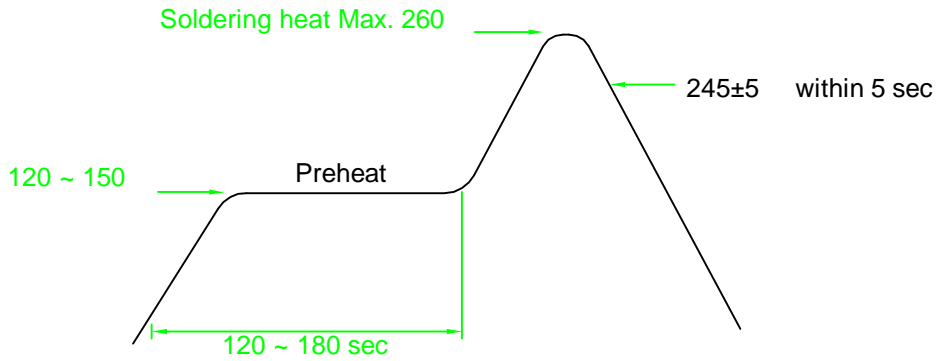


Recommended Soldering Conditions

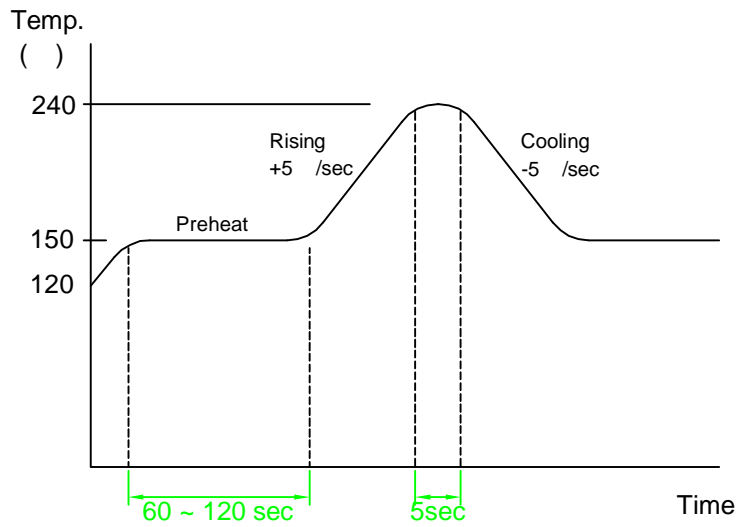
1. Hand Solder

Basic spec is 280 3 sec one time only.

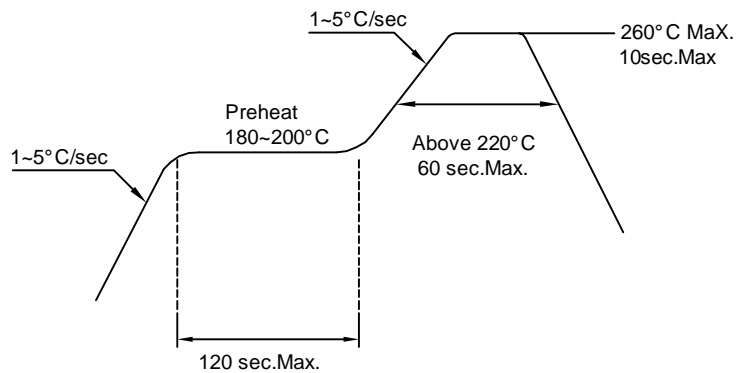
2. Wave Solder



3. LEAD Reflow Solder



4. PB-Free Reflow Solder



Note: 1.Wave solder and reflow soldering should not be made more than one time.
2.You can just only select one of the soldering conditions as above.



Precautions For Use:

Storage time:

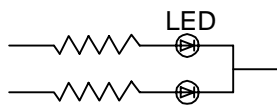
- 1.The operation of Temperatures and RH are : 5 ~35 ,RH<60%.
- 2.Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year(from production date).
- 3.If opened more than one week in an atmosphere 5 ~ 35 ,RH<60%, they should be treated at 60 ±5 fo r 15hrs.

Drive Method:

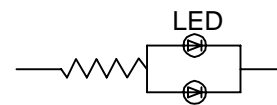
LED is a current operated device, and therefore, requirer some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in series with the LED.

Consider worst case voltage variations than could occur across the current limiting resistor. The forwr d current should not be allowed to change by more than 40 % of its desired value.

Circuit model A



Circuit model B



(A) Recommended circuit.

(B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing these LED. All devices, equipment and machinery must be properly grounded.



Precautions For Use:

Storage time:

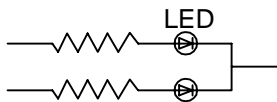
- 1.The operation of Temperatures and RH are : 30 ,RH<60%.
- 2.Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year(from production date).
- 3.If opened more than168hrs in an atmosphere 30 ,RH<60%, The single LED end product must use for 125 for 10hours to eliminate wet
- 4.If opened more than168hrs in an atmosphere 30 ,RH<60%, The reel and carrier end product must use for 60 for 24 hours to eliminate wet

Drive Method:

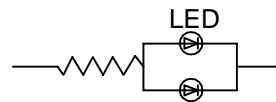
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Circuit model A





Circuit model B



(A) Recommended circuit.

(B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

CAUTION

This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL

3

- 1.Shelf life in sealed bag:12months at 30 and<60 % relative humidity(RH) [Complete package before open the packing]
- 2.Once the package is opened,devices that will be subjected to infrared reflow must be
 - (a)Mounted within 168 hours at factory conditions of 30 /60 % RH
 - (b)Stored at 30 / 10 % RH within 168 hours
 - (c)The aluminum foil bag does out the vacuum
 - (d)From SMT to the IR timing control is 24 hours
- 3.If the humidity indicator 10%RH is pink or after open package 12 hrs house,the led monomer should be treated at125 ±5 for10hrs.
- 4.The reel and carrier end product must use for 60 for 24 hours to eliminate wet
- 5.For the detail,please refer to the standard: IFC JEDEC J-STD-033

Date and time opened:
Note:level and body temperature defined by IPC/JEDEC J-STD-020



Reliability Test:

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operating Life Test	1.Ta=Under Room Temperature As Per Data Sheet Maximum Rating. 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-750D: 1026 MIL-STD-883D: 1005 JIS C 7021: B-1
	High Temperature Storage Test	1.Ta=105 ±5 2.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-883D:1008 JIS C 7021: B-10
	Low Temperature Storage Test	1.Ta=-40 ±5 2.t=1000 hrs (-24hrs, +72hrs)	JIS C 7021: B-12
	High Temperature High Humidity Storage Test	1.IR-Reflow In-Board, 2 Times 2.Ta=65 ±5 3.RH=90%~95% 4.t=1000hrs ±2hrs	MIL-STD-202F:103B JIS C 7021: B-11
Environmental Test	Thermal Shock Test	1.IR-Reflow In-Board,2 times 2.Ta=105 ±5 & -40 ±5 (10min) (10min) 3.total 10 cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1011
	Solder Resistance Test	1.T.Sol=260 ±5 2.Dwell Time= 10 ±1sec.	MIL-STD-202F: 210A MIL-STD-750D: 2031 JIS C 7021: A-1
	Solderability Test	1.T.Sol=235 ±5 2.Immersion time 2 ±0.5sec 3.Immersion rate 25 ±2.5mm/sec 4.Immersion rate 25 ±2.5mm/sec 5.Coverage 95% of the dipped surface	MIL-STD-202F: 208D MIL-STD-750D: 2026 MIL-STD-883D: 2003 IEC 68 Part 2-20 JIS C 7021: A-2
	Temperature Cycling	1.105 ~ 25 ~ 55 ~ 25 30mins 5mins 30mins 5mins 2.10 Cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1010 JIS C 7021: A-4
	Solderability Test	Ramp-up rate(183 to Peak) +3 second max Temp. maintain at 125(±25) 120 seconds max Temp. maintain above 183 60-150 seconds Peak temperature range 235 +5-0 Time within 5 of actual Peak Temperature(tp) 10-30 seconds Ramp-down rate +6 /second max	MIL-STD-750D:2031.2 J-STD-020